



**THE DATASHEET OF
514MAB000107BAG**



ANY-FREQUENCY I²C PROGRAMMABLE XO (100 kHz TO 250 MHz)

Features

- Programmable to any frequency from 100 kHz to 250 MHz
- 0.026 ppb frequency tuning resolution
- Glitch suppression on OE, power on and frequency transitions
- Low jitter operation
- 2- to 4-week lead times
- Total stability includes 10-year aging
- Comprehensive production test coverage includes crystal ESR and DLD
- On-chip LDO for power supply noise filtering
- 3.3, 2.5, or 1.8 V operation
- Differential (LVPECL, LVDS, HCSL) or CMOS output options
- Optional integrated 1:2 CMOS fanout buffer
- Industry standard 5x7, 3.2x5, and 2.5x3.2 mm packages
- -40 to 85 °C operation

Applications

- All-digital PLLs
- DAC+ VCXO replacement
- SONET/SDH/OTN
- 3G-SDI/HD-SDI/SDI
- Datacom
- Industrial automation
- FPGA/ASIC clock generation
- FPGA synchronization

Description

The Si514 user-programmable I²C XO utilizes Skyworks Solutions' advanced PLL technology to provide any frequency from 100 kHz to 250 MHz with programming resolution of 0.026 parts per billion. The Si514 uses a single integrated crystal and Skyworks Solutions' proprietary DSPLL synthesizer to generate any frequency across this range using simple I²C commands. Ultra-fine tuning resolution replaces DACs and VCXOs with an all-digital PLL solution that improves performance where synchronization is necessary or in free-running reference clock applications. This solution provides superior supply noise rejection, simplifying low jitter clock generation in noisy environments. Crystal ESR and DLD are individually production-tested to guarantee performance and enhance reliability.

The Si514 is factory-configurable for a wide variety of user specifications, including startup frequency, I²C address, supply voltage, output format, and stability. Specific configurations are factory-programmed at time of shipment, eliminating long lead times and non-recurring engineering charges associated with custom frequency oscillators.

Functional Block Diagram

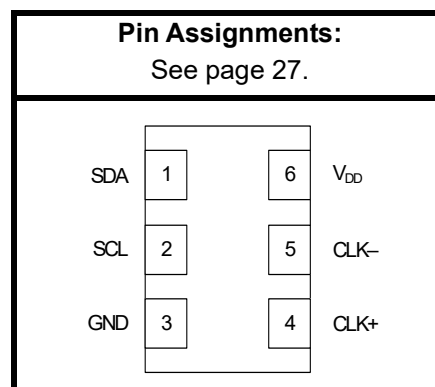
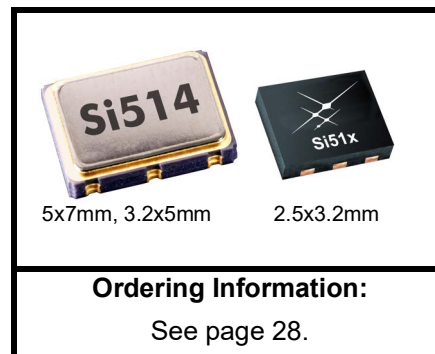
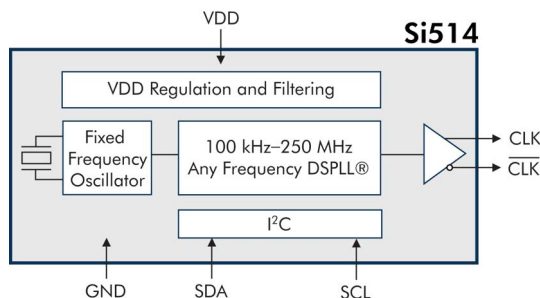


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1. Electrical Specifications

Table 1. Operating Specifications

$V_{DD} = 1.8\text{ V} \pm 5\%$, 2.5 or 3.3 V $\pm 10\%$, $T_A = -40$ to $+85\text{ }^\circ\text{C}$

| Parameter | Symbol | Test Condition | Min | Typ | Max | Units |
|-----------------------|----------|-----------------------------|------|-----|------|------------------|
| Supply Voltage | V_{DD} | 3.3 V option | 2.97 | 3.3 | 3.63 | V |
| | | 2.5 V option | 2.25 | 2.5 | 2.75 | V |
| | | 1.8 V option | 1.71 | 1.8 | 1.89 | V |
| Supply Current | I_{DD} | CMOS, 100 MHz, single-ended | — | 21 | 26 | mA |
| | | LVDS (output enabled) | — | 19 | 23 | mA |
| | | LVPECL (output enabled) | — | 39 | 43 | mA |
| | | HCSL (output enabled) | — | 41 | 44 | mA |
| | | Tristate (output disabled) | — | — | 18 | mA |
| Operating Temperature | T_A | | -40 | — | 85 | $^\circ\text{C}$ |

Table 2. Input Characteristics

$V_{DD} = 1.8\text{ V} \pm 5\%$, 2.5 or 3.3 V $\pm 10\%$, $T_A = -40$ to $+85\text{ }^\circ\text{C}$

| Parameter | Symbol | Test Condition | Min | Typ | Max | Units |
|-----------------------------|----------|----------------|----------------------|-----|----------------------|-------|
| SDA, SCL Input Voltage High | V_{IH} | | $0.80 \times V_{DD}$ | — | — | V |
| SDA, SCL Input Voltage Low | V_{IL} | | — | — | $0.20 \times V_{DD}$ | V |

Si514

Table 3. Output Clock Frequency Characteristics

$V_{DD} = 1.8\text{ V} \pm 5\%$, $2.5\text{ or }3.3\text{ V} \pm 10\%$, $T_A = -40\text{ to }+85\text{ }^\circ\text{C}$

| Parameter | Symbol | Test Condition | Min | Typ | Max | Units |
|--|-----------|--|-------|-------|-------|---------------|
| Programmable Frequency Range | F_O | CMOS, Dual CMOS | 0.1 | — | 212.5 | MHz |
| | F_O | LVDS/LVPECL/HCSL | 0.1 | — | 250 | MHz |
| Frequency Reprogramming Resolution | M_{RES} | | — | 0.026 | — | ppb |
| Frequency Range for Small Frequency Change (Continuous Glitchless Output) | | From center frequency | -1000 | — | +1000 | ppm |
| Settling time for Small Frequency Change | | $\leq \pm 1000$ ppm from center frequency | — | — | 100 | μs |
| Settling time for Large Frequency Change (Output Squelched during Frequency Transition) | | $> \pm 1000$ ppm from center frequency | — | — | 10 | ms |
| Total Stability* | | Frequency Stability Grade C | -30 | — | +30 | ppm |
| | | Frequency Stability Grade B | -50 | — | +50 | ppm |
| | | Frequency Stability Grade A | -100 | — | +100 | ppm |
| Temperature Stability | | Frequency Stability Grade C | -20 | — | +20 | ppm |
| | | Frequency Stability Grade B | -25 | — | +25 | ppm |
| | | Frequency Stability Grade A | -50 | — | +50 | ppm |
| Startup Time | T_{SU} | Minimum V_{DD} until output frequency (F_O) within specification | — | — | 10 | ms |
| Disable Time | T_D | $F_O < 10\text{ MHz}$ | — | — | 40 | μs |
| | | $F_O \geq 10\text{ MHz}$ | — | — | 5 | μs |
| Enable Time | T_E | $F_O < 10\text{ MHz}$ | — | — | 60 | μs |
| | | $F_O \geq 10\text{ MHz}$ | — | — | 20 | μs |
| <p>*Note: Total stability includes initial accuracy, operating temperature, supply voltage change, load change, shock and vibration (not under operation), and 10 years aging at $40\text{ }^\circ\text{C}$.</p> | | | | | | |

Table 4. Output Clock Levels and Symmetry $V_{DD} = 1.8\text{ V} \pm 5\%$, 2.5 or 3.3 V $\pm 10\%$, $T_A = -40$ to $+85\text{ }^\circ\text{C}$

| Parameter | Symbol | Test Condition | Min | Typ | Max | Units |
|---|-----------|--|----------------------|-------------------------|----------------------|------------|
| CMOS Output Logic High | V_{OH} | | $0.85 \times V_{DD}$ | — | — | V |
| CMOS Output Logic Low | V_{OL} | | — | — | $0.15 \times V_{DD}$ | V |
| CMOS Output Logic High Drive | I_{OH} | 3.3 V | -8 | — | — | mA |
| | | 2.5 V | -6 | — | — | mA |
| | | 1.8 V | -4 | — | — | mA |
| CMOS Output Logic Low Drive | I_{OL} | 3.3 V | 8 | — | — | mA |
| | | 2.5 V | 6 | — | — | mA |
| | | 1.8 V | 4 | — | — | mA |
| CMOS Output Rise/Fall Time (20 to 80% V_{DD}) | T_R/T_F | 0.1 to 125 MHz, $C_L = 15\text{ pF}$ | — | 0.8 | 1.2 | ns |
| | | 0.1 to 212.5 MHz, $C_L = \text{no load}$ | — | 0.6 | 0.9 | ns |
| LVPECL/HCSL Output Rise/Fall Time (20 to 80% V_{DD}) | T_R/T_F | | — | — | 565 | ps |
| LVDS Output Rise/Fall Time (20 to 80% V_{DD}) | T_R/T_F | | — | — | 800 | ps |
| LVPECL Output Common Mode | V_{OC} | $50\ \Omega$ to $V_{DD} - 2\text{ V}$, single-ended | — | $V_{DD} - 1.4\text{ V}$ | — | V |
| LVPECL Output Swing | V_O | $50\ \Omega$ to $V_{DD} - 2\text{ V}$, single-ended | 0.55 | 0.8 | 0.90 | V_{PPSE} |
| LVDS Output Common Mode | V_{OC} | 100 Ω line-line, 3.3/2.5 V | 1.13 | 1.23 | 1.33 | V |
| | | 100 Ω line-line, 1.8 V | 0.83 | 0.92 | 1.00 | V |
| LVDS Output Swing | V_O | Single-ended 100 Ω differential termination | 0.25 | 0.35 | 0.45 | V_{PPSE} |
| HCSL Output Common Mode | V_{OC} | 50 Ω to ground | 0.35 | 0.38 | 0.42 | V |
| HCSL Output Swing | V_O | Single-ended | 0.58 | 0.73 | 0.85 | V_{PPSE} |
| Duty Cycle | DC | | 48 | 50 | 52 | % |

Table 5. Output Clock Jitter and Phase Noise (LVPECL)

$V_{DD} = 2.5$ or 3.3 V $\pm 10\%$, $T_A = -40$ to $+85$ °C; Output Format = LVPECL

| Parameter | Symbol | Test Condition | Min | Typ | Max | Units |
|--|----------|--|-----|------|-----|--------|
| Period Jitter (RMS) | JPRMS | 10 k samples ¹ | — | — | 1.3 | ps |
| Period Jitter (Pk-Pk) | JPPKPK | 10 k samples ¹ | — | — | 11 | ps |
| Phase Jitter (RMS) | ϕ_J | 1.875 MHz to 20 MHz integration bandwidth ² (brickwall) | — | 0.31 | 0.5 | ps |
| | | 12 kHz to 20 MHz integration bandwidth ² | — | 0.8 | 1.0 | ps |
| Phase Noise, 156.25 MHz | ϕ_N | 100 Hz | — | -86 | — | dBc/Hz |
| | | 1 kHz | — | -109 | — | dBc/Hz |
| | | 10 kHz | — | -116 | — | dBc/Hz |
| | | 100 kHz | — | -123 | — | dBc/Hz |
| | | 1 MHz | — | -136 | — | dBc/Hz |
| Additive RMS Jitter Due to Power Supply Noise ³ | JPSR | 10 kHz sinusoidal noise | — | 3.0 | — | ps |
| | | 100 kHz sinusoidal noise | — | 3.5 | — | ps |
| | | 500 kHz sinusoidal noise | — | 3.5 | — | ps |
| | | 1 MHz sinusoidal noise | — | 3.5 | — | ps |
| Spurious | SPR | LVPECL output, 156.25 MHz, offset > 10 kHz | — | -75 | — | dBc |

Notes:

1. Applies to output frequencies: 74.17582, 74.25, 75, 77.76, 100, 106.25, 125, 148.35165, 148.5, 150, 155.52, 156.25, 212.5, 250 MHz.
2. Applies to output frequencies: 100, 106.25, 125, 148.35165, 148.5, 150, 155.52, 156.25, 212.5 and 250 MHz.
3. 156.25 MHz. Increase in jitter on output clock due to sinewave noise added to VDD (2.5/3.3 V = 100 mVPP).

Table 6. Output Clock Jitter and Phase Noise (LVDS)

$V_{DD} = 1.8 \text{ V} \pm 5\%$, 2.5 or 3.3 V $\pm 10\%$, $T_A = -40$ to $+85$ °C; Output Format = LVDS

| Parameter | Symbol | Test Condition | Min | Typ | Max | Unit |
|--|----------|--|-----|------|------|--------|
| Period Jitter (RMS) | JPRMS | 10k samples ¹ | — | — | 2.1 | ps |
| Period Jitter (Pk-Pk) | JPPKPK | 10k samples ¹ | — | — | 18 | ps |
| Phase Jitter (RMS) | ϕJ | 1.875 MHz to 20 MHz integration bandwidth ² (brickwall) | — | 0.25 | 0.55 | ps |
| | | 12 kHz to 20 MHz integration bandwidth ² (brickwall) | — | 0.8 | 1.0 | ps |
| Phase Noise, 156.25 MHz | ϕN | 100 Hz | — | -86 | — | dBc/Hz |
| | | 1 kHz | — | -109 | — | dBc/Hz |
| | | 10 kHz | — | -116 | — | dBc/Hz |
| | | 100 kHz | — | -123 | — | dBc/Hz |
| | | 1 MHz | — | -136 | — | dBc/Hz |
| Spurious | SPR | LVPECL output, 156.25 MHz, offset > 10 kHz | — | -75 | — | dBc |
| Notes: | | | | | | |
| 1. Applies to output frequencies: 74.17582, 74.25, 75, 77.76, 100, 106.25, 125, 148.35165, 148.5, 150, 155.52, 156.25, 212.5, 250 MHz. | | | | | | |
| 2. Applies to output frequencies: 100, 106.25, 125, 148.35165, 148.5, 150, 155.52, 156.25, 212.5 and 250 MHz. | | | | | | |

Table 7. Output Clock Jitter and Phase Noise (HCSL)

$V_{DD} = 1.8\text{ V} \pm 5\%$, 2.5 or 3.3 V $\pm 10\%$, $T_A = -40$ to $+85\text{ }^\circ\text{C}$; Output Format = HCSL

| Parameter | Symbol | Test Condition | Min | Typ | Max | Unit |
|-------------------------|----------|--|-----|------|------|--------|
| Period Jitter (RMS) | JPRMS | 10k samples* | — | — | 1.2 | ps |
| Period Jitter (Pk-Pk) | JPPKPK | 10k samples* | — | — | 11 | ps |
| Phase Jitter (RMS) | ϕJ | 1.875 MHz to 20 MHz integration bandwidth* (brickwall) | — | 0.25 | 0.30 | ps |
| | | 12 kHz to 20 MHz integration bandwidth* (brickwall) | — | 0.8 | 1.0 | ps |
| Phase Noise, 156.25 MHz | ϕN | 100 Hz | — | -90 | — | dBc/Hz |
| | | 1 kHz | — | -112 | — | dBc/Hz |
| | | 10 kHz | — | -120 | — | dBc/Hz |
| | | 100 kHz | — | -127 | — | dBc/Hz |
| | | 1 MHz | — | -140 | — | dBc/Hz |
| Spurious | SPR | LVPECL output, 156.25 MHz, offset > 10 kHz | — | -75 | — | dBc |

***Note:** Applies to an output frequency of 100 MHz.

Table 8. Output Clock Jitter and Phase Noise (CMOS, Dual CMOS)

$V_{DD} = 1.8\text{ V} \pm 5\%$, 2.5 or 3.3 V $\pm 10\%$, $T_A = -40$ to $+85\text{ }^\circ\text{C}$; Output Format = CMOS, Dual CMOS

| Parameter | Symbol | Test Condition | Min | Typ | Max | Unit |
|-------------------------|----------|--|-----|------|------|--------|
| Phase Jitter (RMS) | ϕ_J | 1.875 MHz to 20 MHz integration bandwidth ² (brickwall) | — | 0.25 | 0.35 | ps |
| | | 12 kHz to 20 MHz integration bandwidth ² (brickwall) | — | 0.8 | 1.0 | ps |
| Phase Noise, 156.25 MHz | ϕ_N | 100 Hz | — | -86 | — | dBc/Hz |
| | | 1 kHz | — | -108 | — | dBc/Hz |
| | | 10 kHz | — | -115 | — | dBc/Hz |
| | | 100 kHz | — | -123 | — | dBc/Hz |
| | | 1 MHz | — | -136 | — | dBc/Hz |
| Spurious | SPR | LVPECL output, 156.25 MHz, offset > 10 kHz | — | -75 | — | dBc |

Notes:

- Applies to output frequencies: 74.17582, 74.25, 75, 77.76, 100, 106.25, 125, 148.35165, 148.5, 150, 155.52, 156.25, 212.5 MHz.
- Applies to output frequencies: 100, 106.25, 125, 148.35165, 148.5, 150, 155.52, 156.25, 212.5 MHz.

Table 9. Environmental Compliance and Package Information

| Parameter | Conditions/Test Method |
|---------------------------|--------------------------|
| Mechanical Shock | MIL-STD-883, Method 2002 |
| Mechanical Vibration | MIL-STD-883, Method 2007 |
| Solderability | MIL-STD-883, Method 2003 |
| Gross and Fine Leak | MIL-STD-883, Method 1014 |
| Resistance to Solder Heat | MIL-STD-883, Method 2036 |
| Contact Pads | Gold over Nickel |

Table 10. Thermal Characteristics

| Parameter | Symbol | Test Condition | Value | Units |
|---|---------------|----------------|-------|-------|
| CLCC, Thermal Resistance Junction to Ambient* | θ_{JA} | Still air | 110 | °C/W |
| 2x5 x 3.2 mm, Thermal Resistance Junction to Ambient* | θ_{JA} | Still air | 164 | °C/W |

*Note: Applies to 5 x 7 and 3.2 x 5 mm packages.

Table 11. Absolute Maximum Ratings¹

| Parameter | Symbol | Rating | Units |
|---|------------|------------------------|-------|
| Maximum Operating Temperature | T_{AMAX} | 85 | °C |
| Storage Temperature | T_S | -55 to +125 | °C |
| Supply Voltage | V_{DD} | -0.5 to +3.8 | V |
| Input Voltage (any input pin) | V_I | -0.5 to $V_{DD} + 0.3$ | V |
| ESD Sensitivity (HBM, per JESD22-A114) | HBM | 2 | kV |
| Soldering Temperature (Pb-free profile) ² | T_{PEAK} | 260 | °C |
| Soldering Temperature Time at T_{PEAK} (Pb-free profile) ² | T_P | 20–40 | sec |

Notes:

- Stresses beyond those listed in this table may cause permanent damage to the device. Functional operation or specification compliance is not implied at these conditions. Exposure to maximum rating conditions for extended periods may affect device reliability.
- The device is compliant with JEDEC J-STD-020E.

2. Solder Reflow and Rework Requirements for 2.5x3.2 mm Packages

Reflow of Skyworks Solutions' components should be done in a manner consistent with the IPC/JEDEC J-STD-20E standard. The temperature of the package is not to exceed the classification Temperature provided in the standard. The part should not be within -5°C of the classification or peak reflow temperature (T_{PEAK}) for longer than 30 seconds. Key to maintaining the integrity of the component is providing uniform heating and cooling of the part during reflow and rework. Uniform heating is achieved through having a preheat soak and controlling the temperature ramps in the process. J-STD-20E provides minimum and maximum temperatures and times for the preheat/Soak step that need to be followed, even for rework. The entire assembly area should be heated during rework. Hot air should be flowed from both the bottom of the board and the top of the component. Heating from the top only will cause un-even heating of component and can lead to part integrity issues. Temperature Ramp-up rate are not to exceed 3°C/second. Temperature ramp-down rates from peak to final temperature are not to exceed 6°C/second. Time from 25°C to peak temperature is not to exceed 8 min for Pb-free solders.

3. Functional Description

The Si514 offers system designers a programmable, low jitter XO solution with exceptionally fine frequency tuning resolution. To enable designers to take full advantage of this flexibility and performance, Skyworks Solutions provides an easy-to-use evaluation kit and intuitive suite of Windows-based software utilities to simplify the Si514 programming process.

The Si5xx-PROG-EVB kit contains the Programmable Oscillator Software suite and an EVB Driver (USBXpress®) for use with USB-equipped PCs. Go to

www.skyworksinc.com/en/application-pages/Developers for more information.

Alternatively, “3.1. Programming a New Output Frequency” provides designers a detailed description, along with examples, of the frequency programming requirements and process for designers who are interested in learning more about the programming algorithms implemented within the Programmable Oscillator Software suite.

3.1. Programming a New Output Frequency

The output frequency (F_{out}) is determined by programming the feedback multiplier ($M=M_{Int}.M_{Frac}$), High-Speed Divider (HS_DIV), and Low-Speed Divider (LS_DIV) according to the following formula:

$$F_{out} = \frac{F_{XO} \times M}{HS_DIV \times LS_DIV}$$

where $F_{XO} = 31.98\text{MHz}$

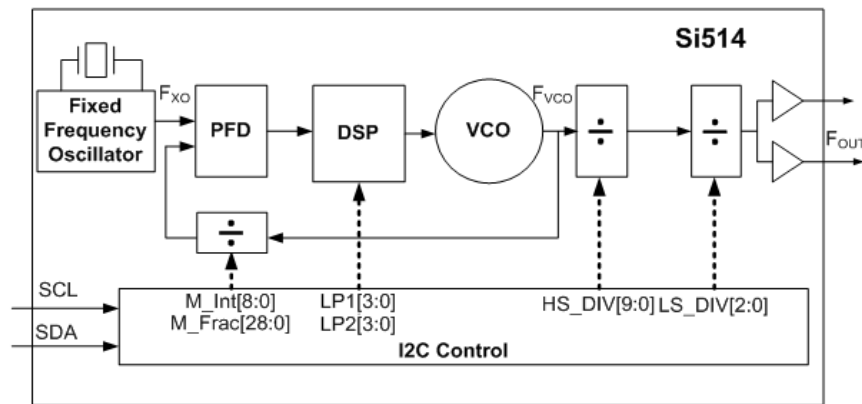


Figure 1. Block Diagram of Si514

The value of the feedback multiplier M is adjustable in the following range:

- $65.04065041 \leq M \leq 78.17385866$.

This keeps the VCO frequency within the range of $2080 \text{ MHz} \leq F_{VCO} \leq 2500 \text{ MHz}$, since the VCO frequency is the product of the internal fixed-frequency crystal (F_{XO}) and the high-resolution 29-bit fractional multiplier (M). This 29-bit resolution of M allows the VCO frequency to have a frequency tuning resolution of 0.026 ppb.

The device comes from the factory with a pre-programmed center frequency within the range of $100 \text{ kHz} \leq F_{OUT} \leq 250 \text{ MHz}$, as specified by the 6-digit code in the part number. (See section “7. Ordering Information” for more information.) To change from the factory-programmed frequency to a different value, the user must follow one of two algorithms based on the magnitude of the frequency change.

- “Small Frequency Change.” To change the frequency by $< \pm 1000$ ppm, the user must keep the same center frequency and only update the value of M . Refer to section “3.2. Programming a Small Frequency Change (sub ± 1000 ppm)” on page 13.
- “Large Frequency Change.” To change the frequency by $\geq \pm 1000$ ppm, the user must change the center frequency. This may require updates to the output dividers (HS_DIV and/or LS_DIV) and possibly the $LP1$ and

LP2 values, in addition to updating the value of M, which requires the VCO to be recalibrated. Refer to section "3.3. Programming a Large Frequency Change (> ±1000 ppm)" on page 14. Figure 2 provides a graphic depiction of the difference between small and large frequency changes.

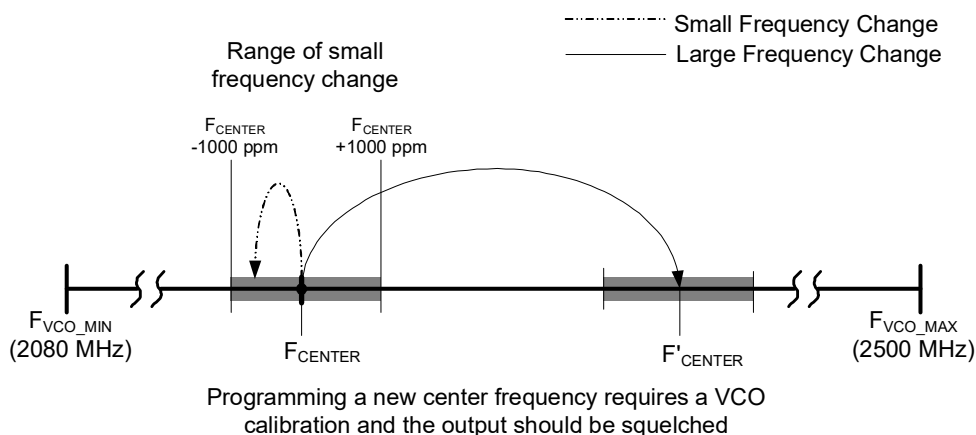


Figure 2. Small vs. Large Frequency Change Illustration

3.2. Programming a Small Frequency Change (sub ±1000 ppm)

The value of the feedback multiplier, M is the only parameter that needs to be updated for output frequency changes less than ±1000 ppm from the center frequency (recalibrating the VCO is NOT required). This enables the output to remain continuous during the change. For example, the output frequency can be swept continuously between 148.5 MHz and 148.352 MHz (i.e., -0.997 ppm) with no output discontinuities or glitches by changing M in either multiple steps or in a single step. For small frequency changes, each update of M requires 100 μs to settle.

Note: It is not possible to implement a frequency change $\geq \pm 1000$ ppm using multiple small frequency changes without changing the center frequency and recalibrating the VCO.

Use the following procedure to make small frequency changes:

1. If the current value of M is already known, then skip to step 2; else, using the serial port, read the current M value (Registers 5-9).
2. Calculate the new value of M as follows (all values are in decimal format):
 - a. $M_{\text{current}} = M_{\text{Int}} + M_{\text{Frac}}/2^{29}$ (Eq 2.2)
 - b. $M_{\text{new}} = M_{\text{current}} \times F_{\text{out_new}} / F_{\text{out_current}}$ (Eq 2.3)
 - c. $M_{\text{Intnew}} = \text{INT}[M_{\text{new}}]^*$ (Eq 2.4)
 - d. $M_{\text{Fracnew}} = (M_{\text{new}} - \text{INT}[M_{\text{new}}]) \times 2^{29}$ (Eq 2.5)

*Where $\text{INT}[n]$ rounds n down to the nearest integer (e.g., $\text{INT}[3.9] = 3$)

3. Using the I²C port, write the new value of M_Frac[23:0] (Not all registers need to be updated.) (Registers: 5, 6, 7)
4. If necessary, write new value of M_Int[2:0] and M_Frac[28:24] register. (Register 8)
5. Write M_Int[8:3]. (Register 9) Frequency changes take effect when M_Int[8:3] is written.

Example 2.1:

An Si514 generating a 148.5 MHz clock must be reconfigured “on-the-fly” to generate a 148.352 MHz clock. This represents a change of -0.996.633 ppm which is within the ±1000 ppm window.

1. Read the current value of M:
 - a. Register 5 = 0xD3 (M_Frac[7:0])
 - b. Register 6 = 0x65 (M_Frac[15:8])
 - c. Register 7 = 0x7C (M_Frac[23:16])

- d. Register 8 = 0x49 (M_Int[2:0],M_Frac[28:24])
 - e. Register 9 = 0x09 (M_Int[8:3])
 - f. M_Int = 0b001001010 = 0x4A = 0d74
 - g. M_Frac = 0x097C65D3 = 159,147,475
 - h. $M = M_Int + M_Frac/2^{29} = 74 + 159,147,475/2^{29} = 74.296435272321105$
2. Calculate Mnew:
- a. $Mnew = 74.296435272321105 \times 148.352/148.5 = 74.2223889933965$
 - b. M_Intnew = 74 = 0x4A
 - c. $M_Fracnew = 0.2223889933965 \times 2^{29} = 119,394,181 = 0x071DCF85$
3. Write Mnew to Registers 5-7:
- a. Register 5 = 0x85
 - b. Register 6 = 0xCF
 - c. Register 7 = 0x1D
4. Write Mnew to Register 8:
- a. Register 8 = 0x47
5. Write Mnew to Register 9:
- a. Register 9 = 0x09

3.3. Programming a Large Frequency Change (> ±1000 ppm)

Large frequency changes are those that vary the F_{VCO} frequency by an amount greater than ±1000 ppm from an operating F_{CENTER} . Figure 2 illustrates the difference between large and small frequency changes. Changing from F_{CENTER} to F'_{CENTER} requires a calibration cycle that resets internal circuitry to establish F'_{CENTER} as the new operating center frequency. The below steps are recommended when performing large frequency changes:

1. Disable the output: Write OE register bit to a 0 (Register 132, bit2)
 2. If using one of the standard frequencies listed in Table 12, then write the new LP1, LP2, M_Frac, M_Int, HS_DIV and LS_DIV register values according to the table (be sure to write M_Int[8:3] (Register 9) after writing to the M_Frac registers (Registers 5-8)). Skip to Step 9. If the desired frequency is not in the table, then follow steps 4-8 below.
 3. Determine the minimum value of LS_DIV (minimizing LS_DIV minimizes the number of dividers on the output stage, thus minimizing jitter) according to the following formula:
 - a. $LS_DIV = F_{VCO}(MIN)/(F_{OUT} \times HS_DIV(MAX))$ (Eq 2.6)
 - b. $LS_DIV = 2080/(F_{OUT}(MHz) \times 1022)$ (Eq 2.7)
 - i. Since LS_DIV is restricted to: dividing by 1,2,4,8,16,32, choose the next largest value over the result derived in Eq 2.7 (e.g., if result is 4.135, choose LS_DIV = 8)
 4. Determine the minimum value for HS_DIV (this optimizes timing margins)
 - a. $HS_DIV(MIN) = F_{VCO}(MIN)/(F_{OUT} \times LS_DIV)$ (Eq 2.8)
 - b. $HS_DIV(MIN) = 2080/(F_{OUT}(MHz) \times LS_DIV)$ (Eq 2.9)
 - i. HS_DIV(MIN) will be the next even number greater than or equal to the result derived in Eq 2.9 (keeping in the range of 10-1022)
- Note:** $SPEED_GRADE_MIN$ (Reg 48) ≤ $LS_DIV \times HS_DIV$ ≤ $SPEED_GRADE_MAX$ (Reg 49); If outside this range, the output will be forced to the disabled state.
5. Determine a value for M according to the following formula (all values are in decimal format):
 - a. $M = LS_DIV \times HS_DIV \times F_{OUT}/F_{XO}$ (Eq 2.10)
 - b. $M = LS_DIV \times HS_DIV \times F_{OUT}(MHz)/31.98$ (Eq 2.11)
 - c. $M_Int = INT[M]$ (Eq 2.12)
 - d. $M_Frac = (M - INT[M]) \times 2^{29}$ (Eq 2.13)

Table 12. Standard Frequency Table

| Fout (MHz) | M | DEC | | HSDIV | LSDIV | LP1 | LP2 | HEX | | HSDIVX | LSDIVX | LP1_X | LP2_X |
|---------------|-------------|-------|-----------|-------|-------|-----|-----|--------|----------|--------|--------|-------|-------|
| | | M_INT | M_FRAC | | | | | M_INTX | M_FRACX | | | | |
| 0.100000 | 65.04065041 | 65 | 21824021 | 650 | 5 | 2 | 2 | 41 | 14D0215 | 28A | 5 | 2 | 2 |
| 1.544000 | 65.08167605 | 65 | 43849494 | 674 | 1 | 2 | 2 | 41 | 29D1716 | 2A2 | 1 | 2 | 2 |
| 2.048000 | 65.06466542 | 65 | 34716981 | 1016 | 0 | 2 | 2 | 41 | 211BD35 | 3F8 | 0 | 2 | 2 |
| 4.096000 | 65.06466542 | 65 | 34716981 | 508 | 0 | 2 | 2 | 41 | 211BD35 | 1FC | 0 | 2 | 2 |
| 4.915200 | 65.16712946 | 65 | 89726943 | 424 | 0 | 2 | 2 | 41 | 5591FDF | 1A8 | 0 | 2 | 2 |
| 19.440000 | 65.65103189 | 65 | 349520087 | 108 | 0 | 2 | 3 | 41 | 14D540D7 | 6C | 0 | 2 | 3 |
| 24.576000 | 66.08930582 | 66 | 47945695 | 86 | 0 | 2 | 3 | 42 | 2DB97DF | 56 | 0 | 2 | 3 |
| 25.000000 | 65.66604128 | 65 | 357578187 | 84 | 0 | 2 | 3 | 41 | 155035CB | 54 | 0 | 2 | 3 |
| 27.000000 | 65.85365854 | 65 | 458304437 | 78 | 0 | 2 | 3 | 41 | 1B512BB5 | 4E | 0 | 2 | 3 |
| 38.880000 | 65.65103189 | 65 | 349520087 | 54 | 0 | 2 | 3 | 41 | 14D540D7 | 36 | 0 | 2 | 3 |
| 44.736000 | 67.14596623 | 67 | 78365022 | 48 | 0 | 2 | 3 | 43 | 4ABC15E | 30 | 0 | 2 | 3 |
| 54.000000 | 67.54221388 | 67 | 291098862 | 40 | 0 | 2 | 3 | 43 | 1159D0EE | 28 | 0 | 2 | 3 |
| 62.500000 | 66.44777986 | 66 | 240399983 | 34 | 0 | 2 | 3 | 42 | E54366F | 22 | 0 | 2 | 3 |
| 65.536000 | 65.57698562 | 65 | 309766794 | 32 | 0 | 2 | 3 | 41 | 1276AA8A | 20 | 0 | 2 | 3 |
| 74.175824 | 69.58332458 | 69 | 313169998 | 30 | 0 | 3 | 3 | 45 | 12AA984E | 1E | 0 | 3 | 3 |
| 74.250000 | 69.65290807 | 69 | 350527350 | 30 | 0 | 3 | 3 | 45 | 14E49F76 | 1E | 0 | 3 | 3 |
| 77.760000 | 68.08255159 | 68 | 44319550 | 28 | 0 | 3 | 3 | 44 | 2A4433E | 1C | 0 | 3 | 3 |
| 106.250000 | 66.44777986 | 66 | 240399983 | 20 | 0 | 2 | 3 | 42 | E54366F | 14 | 0 | 2 | 3 |
| 125.000000 | 70.3564728 | 70 | 191379875 | 18 | 0 | 3 | 3 | 46 | B6839A3 | 12 | 0 | 3 | 3 |
| 148.351648 | 74.22221288 | 74 | 119299633 | 16 | 0 | 3 | 4 | 4A | 71C5E31 | 10 | 0 | 3 | 4 |
| 148.500000 | 74.29643527 | 74 | 159147475 | 16 | 0 | 3 | 4 | 4A | 97C65D3 | 10 | 0 | 3 | 4 |
| 150.000000 | 65.66604128 | 65 | 357578187 | 14 | 0 | 2 | 3 | 41 | 155035CB | E | 0 | 2 | 3 |
| 155.520000 | 68.08255159 | 68 | 44319550 | 14 | 0 | 3 | 3 | 44 | 2A4433E | E | 0 | 3 | 3 |
| 156.250000 | 68.40212633 | 68 | 215889929 | 14 | 0 | 3 | 3 | 44 | CDE3809 | E | 0 | 3 | 3 |
| 212.500000 | 66.44777986 | 66 | 240399983 | 10 | 0 | 2 | 3 | 42 | E54366F | A | 0 | 2 | 3 |
| 250.000000 | 78.17385866 | 78 | 93339658 | 10 | 0 | 4 | 4 | 4E | 590400A | A | 0 | 4 | 4 |

6. Determine values for LP1 and LP2 according to Table 13:

Table 13. LP1, LP2 Values

| Fvco_max | Fvco_min | M_max | M_min | LP1 | LP2 |
|------------------|------------------|--------------|--------------|-----|-----|
| 2500000000.00000 | 2425467616.18572 | 78.173858662 | 75.843265046 | 4 | 4 |
| 2425467616.18572 | 2332545246.89005 | 75.843265046 | 72.937624981 | 3 | 4 |
| 2332545246.89005 | 2170155235.53450 | 72.937624981 | 67.859763463 | 3 | 3 |
| 2170155235.53450 | 2087014168.27005 | 67.859763463 | 65.259980246 | 2 | 3 |
| 2087014168.27005 | 2080000000.00000 | 65.259980246 | 65.040650407 | 2 | 2 |

7. Write new LP1, LP2, M_Frac, M_Int, HS_DIV and LS_DIV register values (be sure to write M_Int[8:3] (Register 9) after writing to the M_Frac registers (Registers 5-8)
8. Write FCAL (Register 132, bit 0) to a 1 (this bit auto-resets, so it will always read as 0).
9. Enable the output: Write OE register bit to a 1.

The Si514 does not automatically detect large frequency changes. The user needs to assert the FCAL register bit to initiate the calibration cycle required to re-center the VCO around the new frequency. Large frequency changes are discontinuous and output may skip to intermediate frequencies or generate glitches. Resetting the OE bit before FCAL will prevent intermediate frequencies from appearing on the output while Si514 completes a calibration cycle and settles to F_{CENTER} . Settling time for large frequency changes is 10 msec maximum.

Example 2.2:

The user has a part that is programmed with SPEED_GRADE_MIN = 20 and SPEED_GRADE_MAX = 250 that is programmed from the factory for $F_{OUT} = 50$ MHz and wants to change to an STS-1 rate of 51.84 MHz. This represents a change of +36,800 ppm which exceeds ± 1000 ppm and therefore requires a large frequency change process.

1. Write Reg 132, bit 2 to a 0 to disable the output.
2. Since 51.84 MHz is not in Table 2.1, the divider parameters must be calculated.
3. Calculate LS_DIV by using Eq 2.7:
 - a. $LS_DIV = 2080 / (51.84 \times 1022) = 0.039$
 - b. Since $0.039 < 1$, use a divide-by-one (bypass), therefore $LS_DIV = 0$
4. Calculate HS_DIV(MIN) by using Eq 2.9:
 - a. $HS_DIV(MIN) = 2080 / (51.84 \times 1) = 40.123$
 - b. Since $40.123 > 40$, use $HS_DIV(MIN) = 42 = 0x2A$
5. From Eq 2.11:
 - a. $M = 1 \times 42 \times 51.84 / 31.98 = 68.08255159474$
 - b. $M_Int = 68 = 0x44$
 - c. $M_Frac = 0.08255259474 \times 2^{29} = 44,320,087 = 0x2A44557$
6. From Table 2.2:
 - a. LP1 = 3
 - b. LP2 = 3

7. Write Registers 0, 5-11:
 - a. Register 0 = 0x33
 - b. Register 5 = 0x57 (M_Frac[7:0])
 - c. Register 6 = 0x45 (M_Frac[15:8])
 - d. Register 7 = 0xA4 (M_Frac[23:16])
 - e. Register 8 = 0x42 (M_Int[2:0],M_Frac[28:24])
 - f. Register 9 = 0x05 (M_Int[8:3])
 - g. Register 10 = 0x2A
 - h. Register 11 = 0x00
8. Calibrate the VCO by writing Register 132, bit 0 to a 1.
9. Enable the output by writing Register 132, bit 2 to a 1.

4. All-Digital PLL Applications

The Si514 uses a high resolution divider M that enables fine frequency adjustments with resolution better than 0.026 parts per billion. Fine frequency adjustments are useful when making frequency corrections that compensate for changing ambient conditions, long term aging or when locking the Si514 to an input clock reference. Figure 3 shows a typical implementation using a system IC such as an FPGA to control the output of the Si514 in a phase-locked application. Refer to “AN575: An Introduction to FPGA-Based ADPLLs” for more information.

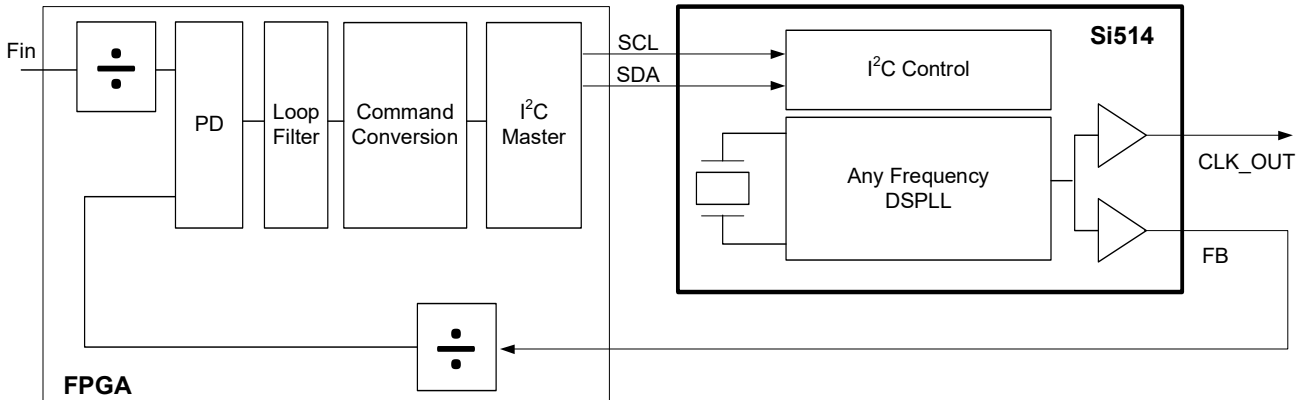


Figure 3. All-Digital PLL Application Using Si514 with Dual CMOS Output

Since small frequency changes must be within ± 1000 ppm of the center frequency, HS_DIV and LS_DIV remain constant. The below expression can be used to calculate a new M_2 divider value based on a desired output frequency shift, where ΔF_{OUT} is in ppm.

$$M_2 = M_1(1 - \Delta F_{OUT} \times 10^{-6})$$

Some systems, particularly those that use feedback control, can simplify the computation by implementing an approximate frequency change based on toggling a bit position or adding/subtracting a bit to the existing M_Frac value. Since M ranges approximately $\pm 10\%$ between 65.04065041 and 78.17385866, the effect of changing M_Frac by a single bit depends only slightly on the absolute value of M.

For $M=71$ near the midpoint of the range, toggling $M_Frac[0]$ changes the output frequency by 0.026 ppb. Each higher order bit doubles the influence such that toggling $M_Frac[1]$ is 0.052 ppb, $M_Frac[2]$ is 0.1 ppb, etc. Figure 4 shows this trend across multiple registers generalized to $M_Frac[N]$. Coarse changes greater than ± 1.7 ppm are possible but most applications require finer transitions. Toggling each bit involves incrementing or decrementing the bit position. Writing $M_Int[8:3]$ in register 9 completes the operation.

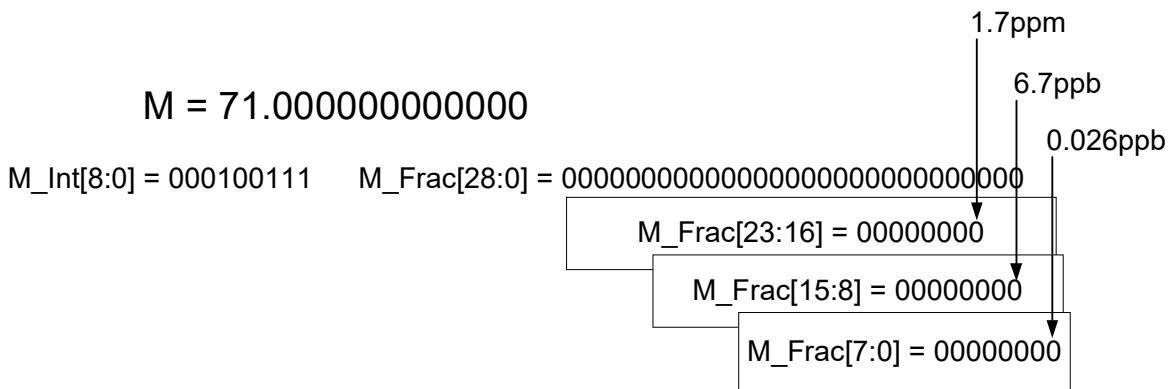


Figure 4. Output Frequency Change When Toggling $M_Frac[N]$, $M=71$

5. User Interface

5.1. Register Map

Table 14 displays the Si514 user register map. Registers not shown are reserved. Registers with reserved bits are read-modify-write.

Table 14. User Register Map

| Address | Bit | | | | | | | |
|---------|----------------|---------------|----------------|----------------|----------|----|--------------|------|
| | 7 | 6 | 5 | 4 | 3 | 2 | 1 | 0 |
| 0 | LP1[3:0] | | | | LP2[3:0] | | | |
| 5 | M_Frac [7:0] | | | | | | | |
| 6 | M_Frac [15:8] | | | | | | | |
| 7 | M_Frac [23:16] | | | | | | | |
| 8 | M_Int [2:0] | | | M_Frac [28:24] | | | | |
| 9 | | | M_Int [8:3] | | | | | |
| 10 | HS_DIV [7:0] | | | | | | | |
| 11 | | LS_DIV [2:0] | | | | | HS_DIV [9:8] | |
| 14 | | | OE_STATE [1:0] | | | | | |
| 128 | RST | | | | | | | |
| 132 | | | | | | OE | | FCAL |

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5.2. Register Detailed Description

Note: Registers not shown are reserved. Registers with reserved bits are read-modify-write.

Register 0.

| Bit | 7 | 6 | 5 | 4 | 3 | 2 | 1 | 0 |
|---------|----------|---|---|---|----------|---|---|---|
| Name | LP1[3:0] | | | | LP2[3:0] | | | |
| Type | R/W | | | | R/W | | | |
| Default | Varies | | | | Varies | | | |

| Bit | Name | Function |
|-----|----------|--|
| 7:4 | LP1[3:0] | Sets loop compensation factor LP1. Value depends on VCO frequency. |
| 3:0 | LP2[3:0] | Sets loop compensation factor LP2. Value depends on VCO frequency. |

Register 5.

| Bit | 7 | 6 | 5 | 4 | 3 | 2 | 1 | 0 |
|---------|-------------|---|---|---|---|---|---|---|
| Name | M_Frac[7:0] | | | | | | | |
| Type | R/W | | | | | | | |
| Default | Varies | | | | | | | |

| Bit | Name | Function |
|-----|-------------|--|
| 7:0 | M_Frac[7:0] | Fractional part of feedback divider M that sets up the output frequency. Frequency updates take effect when M_Int[8:3] is written. |

Register 6.

| Bit | 7 | 6 | 5 | 4 | 3 | 2 | 1 | 0 |
|---------|--------------|---|---|---|---|---|---|---|
| Name | M_Frac[15:8] | | | | | | | |
| Type | R/W | | | | | | | |
| Default | Varies | | | | | | | |

| Bit | Name | Function |
|-----|--------------|--|
| 7:0 | M_Frac[15:8] | Fractional part of feedback divider M that sets up the output frequency. Frequency updates take effect when M_Int[8:3] is written. |

Register 7.

| Bit | 7 | 6 | 5 | 4 | 3 | 2 | 1 | 0 |
|----------------|---------------|---|---|---|---|---|---|---|
| Name | M_Frac[23:16] | | | | | | | |
| Type | R/W | | | | | | | |
| Default | Varies | | | | | | | |

| Bit | Name | Function |
|-----|---------------|--|
| 7:0 | M_Frac[23:16] | Fractional part of feedback divider M that sets up the output frequency. Frequency updates take effect when M_Int[8:3] is written. |

Register 8.

| Bit | 7 | 6 | 5 | 4 | 3 | 2 | 1 | 0 |
|----------------|------------|---|---|---------------|---|---|---|---|
| Name | M_Int[2:0] | | | M_Frac[28:24] | | | | |
| Type | R/W | | | R/W | | | | |
| Default | Varies | | | Varies | | | | |

| Bit | Name | Function |
|-----|---------------|--|
| 7:5 | M_Int[2:0] | Integer part of feedback divider M that sets the output frequency. Frequency updates take effect when M_Int[8:3] is written. |
| 4:0 | M_Frac[28:24] | Fractional part of feedback divider M that sets up the output frequency. Frequency updates take effect when M_Int[8:3] is written. |

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Register 9.

| Bit | 7 | 6 | 5 | 4 | 3 | 2 | 1 | 0 |
|---------|--------|-----|------------|---|---|---|---|---|
| Name | | | M_Int[8:3] | | | | | |
| Type | R/W | R/W | R/W | | | | | |
| Default | Varies | | | | | | | |

| Bit | Name | Function |
|-----|------------|--|
| 7:6 | Reserved | |
| 5:0 | M_Int[8:3] | Integer part of feedback divider M that sets the output frequency. Frequency updates take effect when M_Int[8:3] is written. |

Register 10.

| Bit | 7 | 6 | 5 | 4 | 3 | 2 | 1 | 0 |
|---------|-------------|---|---|---|---|---|---|---|
| Name | HS_DIV[7:0] | | | | | | | |
| Type | R/W | | | | | | | |
| Default | Varies | | | | | | | |

| Bit | Name | Function |
|-----|-------------|---|
| 7:0 | HS_DIV[7:0] | Integer divider that divides VCO frequency and provides output to LS_DIV. Follow the large frequency change procedure when updating. The allowed values are even numbers in the range from 10 to 1022 (i.e., 10, 12, 14, 16, ..., 1022). The decimal value represents the actual divide value (i.e. 12 means divide-by-12). |

Register 11.

| Bit | 7 | 6 | 5 | 4 | 3 | 2 | 1 | 0 |
|---------|-----|-------------|---|---|-----|-----|-------------|---|
| Name | | LS_DIV[2:0] | | | | | HS_DIV[9:8] | |
| Type | R/W | R/W | | | R/W | R/W | R/W | |
| Default | | Varies | | | | | Varies | |

| Bit | Name | Function |
|-----|-------------|--|
| 7 | Reserved | |
| 6:4 | LS_DIV[2:0] | Last output divider stage. Used during large frequency changes. To update, follow large frequency change procedure. LS_DIV value updates asynchronously. 000: divide-by-1 001: divide-by-2 010: divide-by-4 011: divide-by-8 100: divide-by-16 101: divide-by-32 All others reserved. |
| 3:2 | Reserved | |
| 1:0 | HS_DIV[9:8] | Integer divider that divides VCO frequency and provides output to LS-DIV. Follow the large frequency change procedure when updating. The allowed values are even numbers in the range from 10 to 1022 (i.e., 10, 12, 14, 16, ..., 1022). The decimal value represents the actual divide value (i.e., 12 means divide-by-12). |

Register 14.

| Bit | 7 | 6 | 5 | 4 | 3 | 2 | 1 | 0 |
|---------|-----|-----|---------------|---|-----|-----|-----|-----|
| Name | | | OE_STATE[1:0] | | | | | |
| Type | R/W | R/W | R/W | | R/W | R/W | R/W | R/W |
| Default | | | 0 | 0 | | | | |

| Bit | Name | Function |
|-----|---------------|---|
| 7:6 | Reserved | |
| 5:4 | OE_STATE[1:0] | Sets logic state of output when output disabled. 00: high impedance 10: logic low when output disabled 01: logic high when output disabled 11: reserved |
| 3:0 | Reserved | |

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Register 128.

| Bit | 7 | 6 | 5 | 4 | 3 | 2 | 1 | 0 |
|---------|-----|-----|-----|-----|-----|-----|-----|-----|
| Name | RST | | | | | | | |
| Type | R/W | R/W | R/W | R/W | R/W | R/W | R/W | R/W |
| Default | 0 | | | | | | | |

| Bit | Name | Function |
|-----|----------|--|
| 7 | RST | Global Reset. Resets all register values to default values. Self-clearing. |
| 6:0 | Reserved | |

Register 132.

| Bit | 7 | 6 | 5 | 4 | 3 | 2 | 1 | 0 |
|---------|-----|-----|-----|-----|-----|-----|-----|------|
| Name | | | | | | OE | | FCAL |
| Type | R/W | R/W | R/W | R/W | R/W | R/W | R/W | R/W |
| Default | | | | | | 1 | | 0 |

| Bit | Name | Function |
|-----|----------|--|
| 7:3 | Reserved | |
| 2 | OE | Output Enable. OE can stop in high, low or high impedance state. 1: Output driver enabled. 0: Output driver powered down. OE_STATE register determines output state when disabled. |
| 1 | Reserved | |
| 0 | FCAL | Initiates frequency calibration cycle. Necessary when making large frequency changes. Frequency calibration cycle takes 10 msec maximum. To prevent intermediate frequencies on the output, set disable output using OE register. Self-clearing. |

5.3. I²C Interface

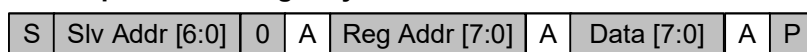
Configuration and operation of the Si514 is controlled by reading and writing to the RAM space using the I²C interface. The device operates in slave mode with 7-bit addressing and can operate in Standard-Mode (100 kbps) or Fast-Mode (400 kbps). Burst data transfer with auto address increments are also supported.

The I²C bus consists of a bidirectional serial data line (SDA) and a serial clock input (SCL). Both the SDA and SCL pins must be connected to the VDD supply via an external pull-up as recommended by the I²C specification. The Si514 7-bit I²C slave address is user-customized during the part number configuration process. See "6. Pin Descriptions" on page 27 for more details.

Data is transferred MSB first in 8-bit words as specified by the I²C specification. A write command consists of a 7-bit device (slave) address + a write bit, an 8-bit register address, and 8 bits of data as shown in Figure 5.

A write burst operation is also shown where every additional data word is written using an auto-incremented address.

Write Operation – Single Byte



Write Operation - Burst (Auto Address Increment)

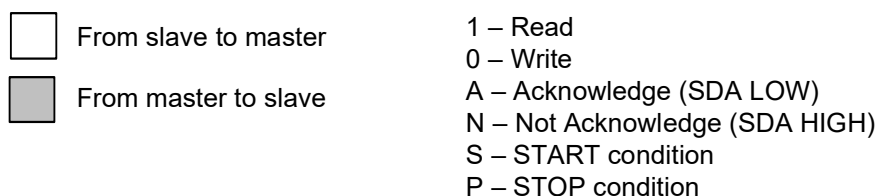
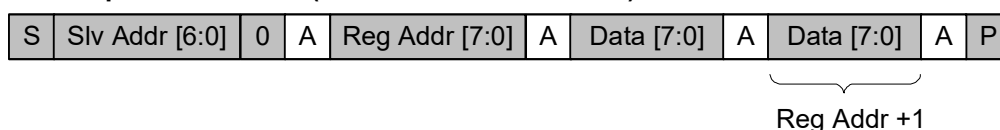
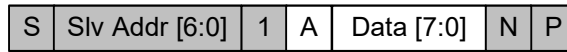
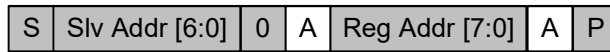


Figure 5. I²C Write Operation

A read operation is performed in two stages. A data write is used to set the register address, then a data read is performed to retrieve the data from the set address. A read burst operation is also supported. This is shown in Figure 6.

Read Operation – Single Byte



Read Operation - Burst (Auto Address Increment)

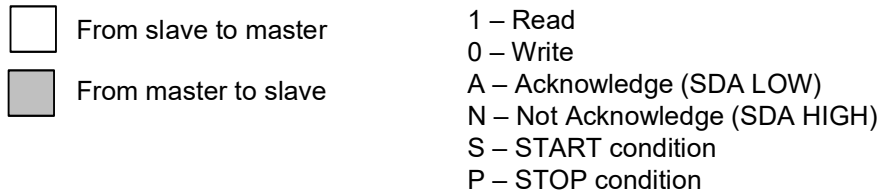
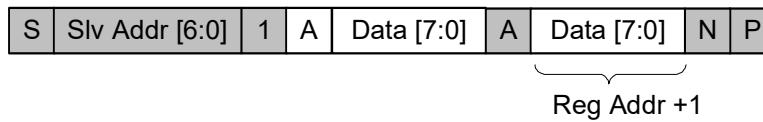
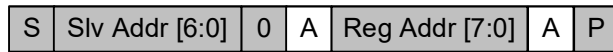


Figure 6. I²C Read Operation

The timing specifications and timing diagram for the I²C bus is compatible with the I²C-Bus standard. SDA timeout is supported for compatibility with SMBus interfaces.

The I²C bus can be operated at a bus voltage of 1.71 to 3.63 V and is 3.3 V tolerant.

6. Pin Descriptions

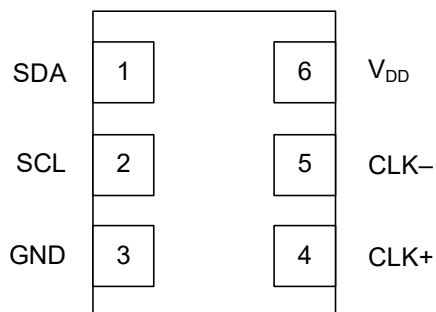


Table 15. Si514 Pin Descriptions

| Pin | Name | Function |
|-----|-----------------|--|
| 1 | SDA | I ² C Serial Data. |
| 2 | SCL | I ² C Serial Clock. |
| 3 | GND | Electrical and Case Ground. |
| 4 | CLK+ | Clock Output. |
| 5 | CLK- | Complementary clock output (LVPECL, LVDS, HCSL, and Complementary dual CMOS formats). Clock output for in-phase dual CMOS format. No connect (N/C) for single-ended CMOS format. |
| 6 | V _{DD} | Power Supply Voltage. |

6.1. Dual CMOS (1:2 Fanout Buffer)

Dual CMOS output format ordering options support either complementary or in-phase output signals. This feature enables replacement of multiple XOs with a single Si514 device.

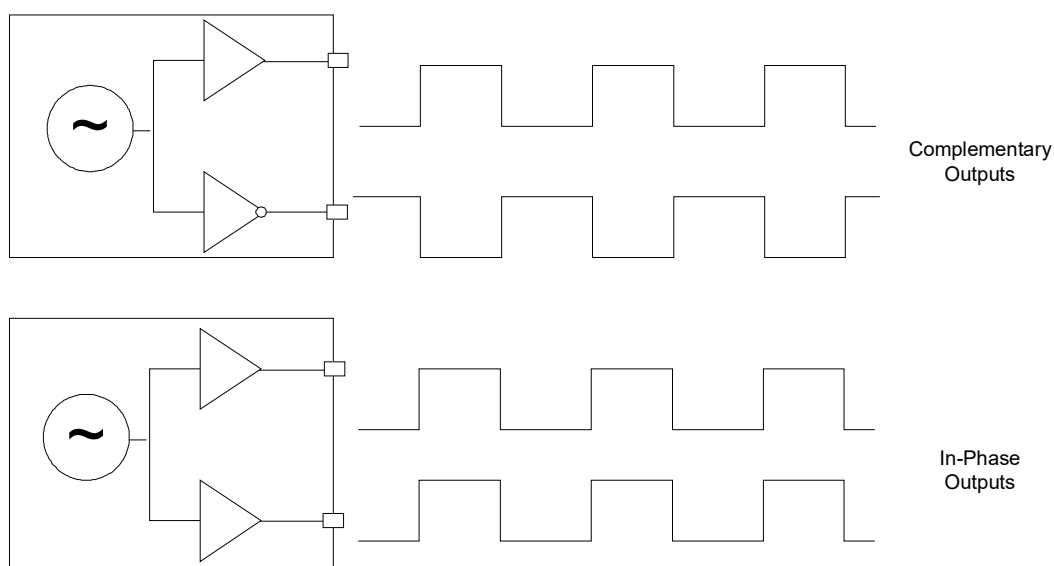


Figure 7. Integrated 1:2 CMOS Buffer Supports Complementary or In-Phase Outputs

7. Ordering Information

The Si514 supports a wide variety of options including startup frequency, stability, output format, and VDD. Specific device configurations are programmed into the Si514 at time of shipment. Configurations can be specified using the Part Number Configuration chart below. Skyworks Solutions provides a web browser-based part number configuration utility to simplify this process. To access this tool refer to www.skyworksinc.com/products/timing-oscillators and click “Customize” in the product table. The Si514 XO series is supplied in industry-standard, RoHS-compliant, 2.5 x 3.2 mm, 3.2 x 5.0 mm, and 5 x 7 mm packages. Tape and reel packaging is an ordering option.

| Series | Output Format | Package |
|--------|--------------------------------------|---------|
| 514 | LVPECL, LVDS, HCSSL, CMOS, Dual CMOS | 6-pin |

A = Revision: A
 G = Temp Range: -40°C to 85°C
 R = Tape & Reel; Blank = Coil Tape

1st Option Code:
Output Format

| | VDD | Output Format |
|---|------|---------------------------|
| A | 3.3V | LVPECL |
| B | 3.3V | LVDS |
| C | 3.3V | CMOS |
| D | 3.3V | HCSSL |
| E | 2.5V | LVPECL |
| F | 2.5V | LVDS |
| G | 2.5V | CMOS |
| H | 2.5V | HCSSL |
| J | 1.8V | LVDS |
| K | 1.8V | CMOS |
| L | 1.8V | HCSSL |
| M | 3.3V | Dual CMOS (In-phase) |
| N | 3.3V | Dual CMOS (Complementary) |
| P | 2.5V | Dual CMOS (In-phase) |
| Q | 2.5V | Dual CMOS (Complementary) |
| R | 1.8V | Dual CMOS (In-phase) |
| S | 1.8V | Dual CMOS (Complementary) |



3rd Option Code:
Frequency Grade

| | CMOS (MHz) | LVPECL, LVDS, HCSSL (MHz) |
|---|--------------|---------------------------|
| A | 0.1 to 212.5 | 0.1 to 250 |
| B | 0.1 to 170 | 0.1 to 170 |
| C | 0.1 to 125 | 0.1 to 125 |

Package Option

| | Dimensions |
|---|--------------|
| A | 5 x 7 mm |
| B | 3.2 x 5 mm |
| C | 2.5 x 3.2 mm |

2nd Option Code:
Frequency Stability

| | Total | Temperature |
|---|---------|-------------|
| A | ±100ppm | ±50ppm |
| B | ±50ppm | ±25ppm |
| C | ±30ppm | ±20ppm |

6-digit Frequency and Default I²C Address Code

| Code | Description |
|--------|--|
| xxxxxx | The Si514 supports a user-defined start-up frequency which must be in the same range as specified by the Frequency Grade code. A user-defined, 7-bit I ² C address is supported. Each unique start-up frequency/I ² C address combination is assigned a 6-digit code by: (see ** below). |

** www.skyworksinc.com/en/application-pages/timing-lookup-customize

Figure 8. Part Number Convention

Example orderable part number: 514ECB000107AAG supports 2.5 V LVPECL, ±30 ppm total stability, user programmable output frequency range from 100 kHz to 170 MHz, 5x7 mm package and -40 to 85 °C temperature range. The frequency code designates 10 MHz startup with I²C address of 0x55. Refer to www.silabs.com/VCXO lookup to look up the attributes of any Skyworks Solutions orderable XO/VCXO part number.

Note: CMOS and Dual CMOS maximum frequency is 212.5 MHz.

8. Package Outline Diagram: 5 x 7 mm, 6-pin

Figure 9 illustrates the 5 x 7 mm, 6-pin package details for the Si514. Table 16 lists the values for the dimensions shown in the illustration.

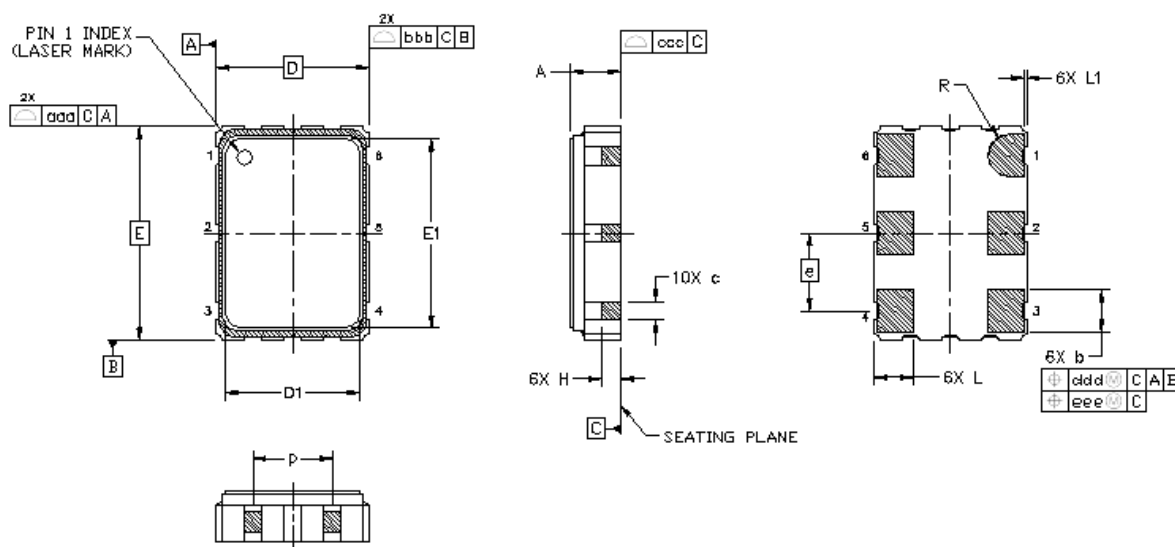


Figure 9. Si514 Outline Diagram

Table 16. Package Diagram Dimensions (mm)

| Dimension | Min | Nom | Max |
|---|----------|------|------|
| A | 1.50 | 1.65 | 1.80 |
| b | 1.30 | 1.40 | 1.50 |
| c | 0.50 | 0.60 | 0.70 |
| D | 5.00 BSC | | |
| D1 | 4.30 | 4.40 | 4.50 |
| e | 2.54 BSC | | |
| E | 7.00 BSC | | |
| E1 | 6.10 | 6.20 | 6.30 |
| H | 0.55 | 0.65 | 0.75 |
| L | 1.17 | 1.27 | 1.37 |
| L1 | 0.05 | 0.10 | 0.15 |
| p | 1.80 | — | 2.60 |
| R | 0.70 REF | | |
| aaa | 0.15 | | |
| bbb | 0.15 | | |
| ccc | 0.10 | | |
| ddd | 0.10 | | |
| eee | 0.05 | | |
| Notes: | | | |
| 1. All dimensions shown are in millimeters (mm) unless otherwise noted. | | | |
| 2. Dimensioning and Tolerancing per ANSI Y14.5M-1994. | | | |

9. PCB Land Pattern: 5 x 7 mm, 6-pin

Figure 10 illustrates the 5 x 7 mm, 6-pin PCB land pattern for the Si514. Table 17 lists the values for the dimensions shown in the illustration.

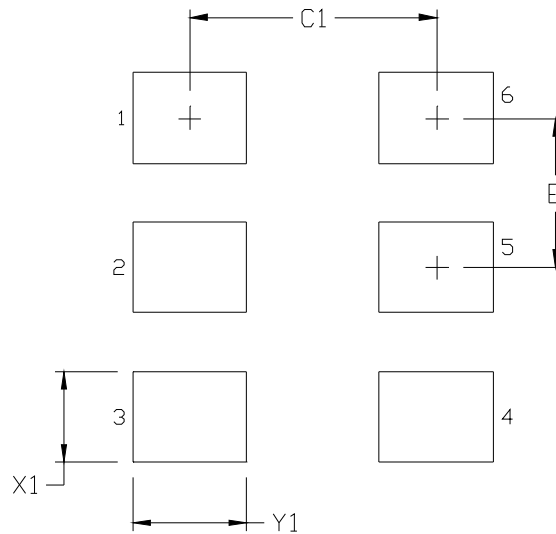


Figure 10. Si514 PCB Land Pattern

Table 17. PCB Land Pattern Dimensions (mm)

| Dimension | (mm) |
|-----------|------|
| C1 | 4.20 |
| E | 2.54 |
| X1 | 1.55 |
| Y1 | 1.95 |

Notes:

General

1. All dimensions shown are in millimeters (mm) unless otherwise noted.
2. Dimensioning and Tolerancing is per the ANSI Y14.5M-1994 specification.
3. This Land Pattern Design is based on the IPC-7351 guidelines.
4. All dimensions shown are at Maximum Material Condition (MMC). Least Material Condition (LMC) is calculated based on a Fabrication Allowance of 0.05 mm.

Solder Mask Design

5. All metal pads are to be non-solder mask defined (NSMD). Clearance between the solder mask and the metal pad is to be 60 μm minimum, all the way around the pad.

Stencil Design

6. A stainless steel, laser-cut and electro-polished stencil with trapezoidal walls should be used to assure good solder paste release.
7. The stencil thickness should be 0.125 mm (5 mils).
8. The ratio of stencil aperture to land pad size should be 1:1.

Card Assembly

9. A No-Clean, Type-3 solder paste is recommended.
10. The recommended card reflow profile is per the JEDEC/IPC J-STD-020 specification for Small Body Components.

10. Package Outline Diagram: 3.2 x 5.0 mm, 6-pin

Figure illustrates the 3.2 x 5 mm package details for the Si514. Table 18 lists the values for the dimensions shown in the illustration.

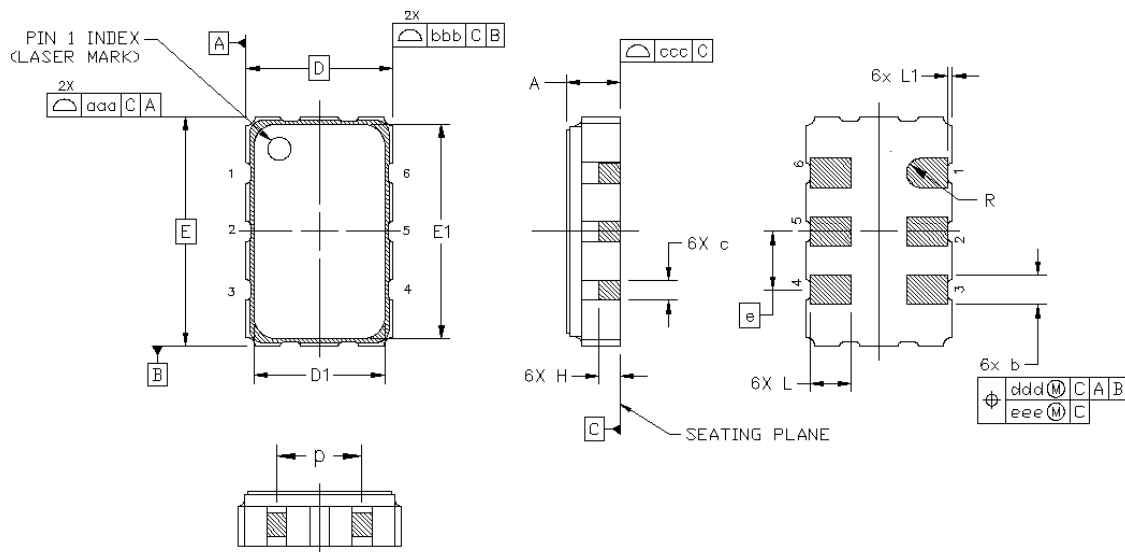


Figure 11. Si514 Outline Diagram

Table 18. Package Diagram Dimensions (mm)

| Dimension | Min | Nom | Max |
|---|----------|------|------|
| A | 1.06 | 1.17 | 1.33 |
| b | 0.54 | 0.64 | 0.74 |
| c | 0.35 | 0.45 | 0.55 |
| D | 3.20 BSC | | |
| D1 | 2.55 | 2.60 | 2.65 |
| e | 1.27 BSC | | |
| E | 5.00 BSC | | |
| E1 | 4.35 | 4.40 | 4.45 |
| H | 0.45 | 0.55 | 0.65 |
| L | 0.80 | 0.90 | 1.00 |
| L1 | 0.05 | 0.10 | 0.15 |
| p | 1.17 | 1.27 | 1.37 |
| R | 0.32 REF | | |
| aaa | 0.15 | | |
| bbb | 0.15 | | |
| ccc | 0.10 | | |
| ddd | 0.10 | | |
| eee | 0.05 | | |
| Notes: | | | |
| 1. All dimensions shown are in millimeters (mm) unless otherwise noted. | | | |
| 2. Dimensioning and Tolerancing per ANSI Y14.5M-1994. | | | |

11. PCB Land Pattern: 3.2 x 5.0 mm, 6-pin

Figure 12 illustrates the 3.2 x 5.0 mm PCB land pattern for the Si514. Table 19 lists the values for the dimensions shown in the illustration.

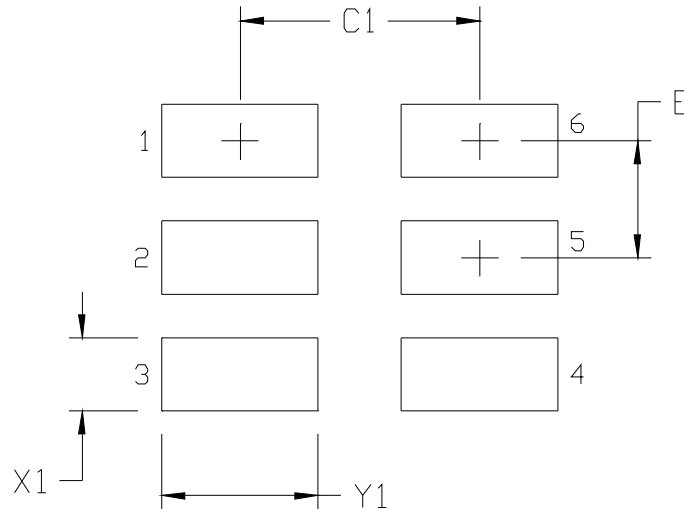


Figure 12. Si514 Recommended PCB Land Pattern

Table 19. PCB Land Pattern Dimensions (mm)

| Dimension | (mm) |
|-----------|------|
| C1 | 2.60 |
| E | 1.27 |
| X1 | 0.80 |
| Y1 | 1.70 |

Notes:

General

- All dimensions shown are in millimeters (mm) unless otherwise noted.
- Dimensioning and Tolerancing is per the ANSI Y14.5M-1994 specification.
- This Land Pattern Design is based on the IPC-7351 guidelines.
- All dimensions shown are at Maximum Material Condition (MMC). Least Material Condition (LMC) is calculated based on a Fabrication Allowance of 0.05 mm.

Solder Mask Design

- All metal pads are to be non-solder mask defined (NSMD). Clearance between the solder mask and the metal pad is to be 60 µm minimum, all the way around the pad.

Stencil Design

- A stainless steel, laser-cut and electro-polished stencil with trapezoidal walls should be used to assure good solder paste release.
- The stencil thickness should be 0.125 mm (5 mils).
- The ratio of stencil aperture to land pad size should be 1:1.

Card Assembly

- A No-Clean, Type-3 solder paste is recommended.
- The recommended card reflow profile is per the JEDEC/IPC J-STD-020 specification for Small Body Components.

12. Package Outline Diagram: 2.5 x 3.2 mm, 6-pin

Figure 13 illustrates the package details for the 2.5 x 3.2 mm Si514. Table 20 lists the values for the dimensions shown in the illustration.

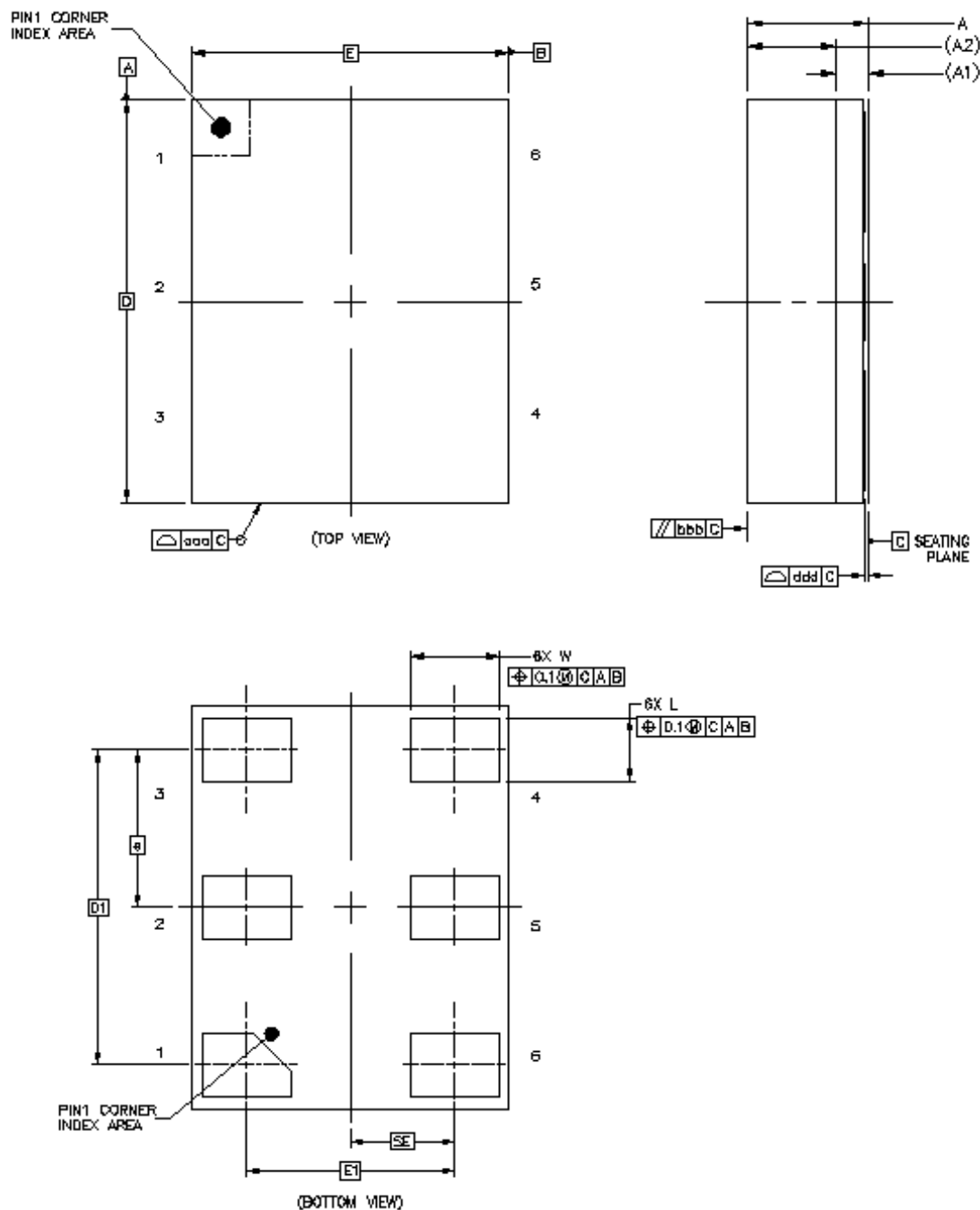


Figure 13. Si514 Outline Diagram

Table 20. Package Diagram Dimensions (mm)

| Dimension | Min | Nom | Max |
|---|-----------|-----|------|
| A | — | — | 1.1 |
| A1 | 0.26 REF | | |
| A2 | 0.7 REF | | |
| W | 0.65 | 0.7 | 0.75 |
| D | 3.20 BSC | | |
| e | 1.25 BSC | | |
| E | 2.50 BSC | | |
| M | 0.30 BSC | | |
| L | 0.45 | 0.5 | 0.55 |
| D1 | 2.5 BSC | | |
| E1 | 1.65 BSC | | |
| SE | 0.825 BSC | | |
| aaa | 0.1 | | |
| bbb | 0.2 | | |
| ddd | 0.08 | | |
| Notes: | | | |
| 1. All dimensions shown are in millimeters (mm) unless otherwise noted. | | | |
| 2. Dimensioning and Tolerancing per ANSI Y14.5M-1994. | | | |

13. PCB Land Pattern: 2.5 x 3.2 mm, 6-pin

Figure 14 illustrates the 2.5 x 3.2 mm PCB land pattern for the Si514. Table 21 lists the values for the dimensions shown in the illustration.

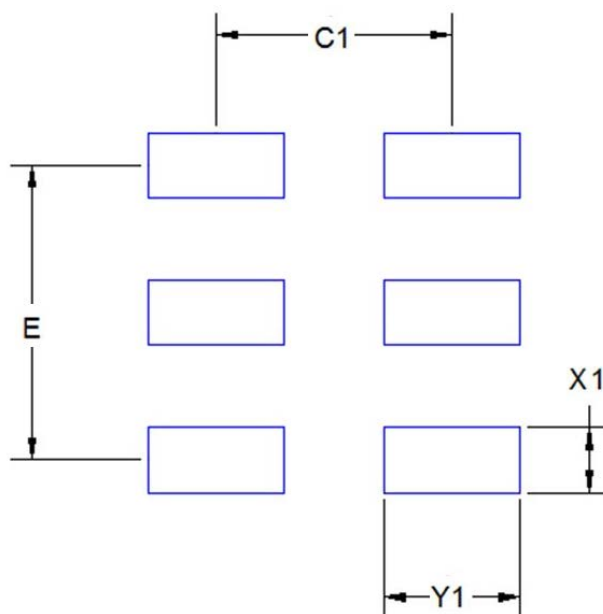


Figure 14. Si514 Recommended PCB Land Pattern

Table 21. PCB Land Pattern Dimensions (mm)

| Dimension | (mm) |
|-----------|------|
| C1 | 1.9 |
| E | 2.50 |
| X1 | 0.70 |
| Y1 | 1.05 |

Notes:

General

- All dimensions shown are at Maximum Material Condition (MMC). Least Material Condition (LMC) is calculated based on a Fabrication Allowance of 0.05 mm.
- This Land Pattern Design is based on the IPC-7351 guidelines.

Solder Mask Design

- All metal pads are to be non-solder mask defined (NSMD). Clearance between the solder mask and the metal pad is to be 60 μm minimum, all the way around the pad.

Stencil Design

- A stainless steel, laser-cut and electro-polished stencil with trapezoidal walls should be used to assure good solder paste release.
- The stencil thickness should be 0.125 mm (5 mils).
- The ratio of stencil aperture to land pad size should be 1:1 for all perimeter pins.

Card Assembly

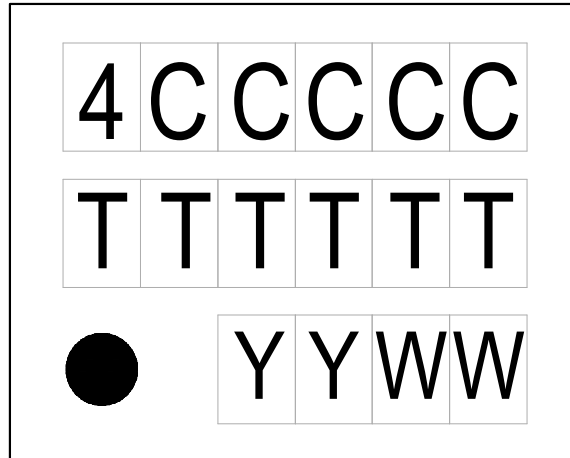
- A No-Clean, Type-3 solder paste is recommended.
- The recommended card reflow profile is per the JEDEC/IPC J-STD-020 specification for Small Body Components.

Si514

14. Top Marking

Use the utility located at: www.skyworksinc.com/en/application-pages/timing-lookup-customize to cross-reference the marked code to a specific device configuration.

14.1. Si514 Top Marking



14.2. Top Marking Explanation

| | | |
|------------------------|--|--|
| Mark Method: | Laser | |
| Line 1 Marking: | 4 = Si514 CCCCC = Mark Code | 4CCCCC |
| Line 2 Marking: | TTTTT = Assembly Manufacturing Code | TTTTTT |
| Line 3 Marking: | Pin 1 indicator. | Circle with 0.5 mm diameter; left-justified |
| | YY = Year. WW = Work week. Characters correspond to the year and work week of package assembly. | YYWW |

REVISION HISTORY

Revision 1.2

June, 2018

- Changed “Trays” to “Coil Tape” in Ordering Guide.

Revision 1.1

December, 2017

- Added new 2.5 x 3.2 mm package.

Revision 1.0

- Updated Table 1 on page 3.
 - Updates to supply current typical and maximum values for CMOS, LVDS, LVPECL and HCSL.
 - CMOS frequency test condition corrected to 100 MHz.
 - Updates to OE VIH minimum and VIL maximum values.
- Updated Table 2 on page 3.
 - Dual CMOS nominal frequency maximum added.
 - Total stability footnotes clarified for 10 year aging at 40 °C.
 - Disable time maximum values updated.
 - Enable time parameter added.
- Updated Table 3 on page 4.
 - CMOS output rise / fall time typical and maximum values updated.
 - LVPECL/HCSL output rise / fall time maximum value updated.
 - LVPECL output swing maximum value updated.
 - LVDS output common mode typical and maximum values updated.
 - HCSL output swing maximum value updated.
 - Duty cycle minimum and maximum values tightened to 48/52%.
- Updated Table 5 on page 6.
 - Phase jitter test condition and maximum value updated.
 - Phase noise typical values updated.
 - Additive RMS jitter due to external power supply noise typical values updated.
 - Footnote 3 updated limiting the VDD to 2.5/3.3V
- Added Tables 6, 7, 8 for LVDS, HCSL, CMOS, and Dual CMOS operations.
- Moved Absolute Maximum Ratings table.
- Added note to Figure 8 clarifying CMOS and Dual CMOS maximum frequency.
- Updated Figure 9 outline diagram to correct pinout.
- Updated “14. Top Marking” section and moved to page 36.



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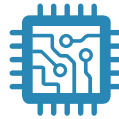
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